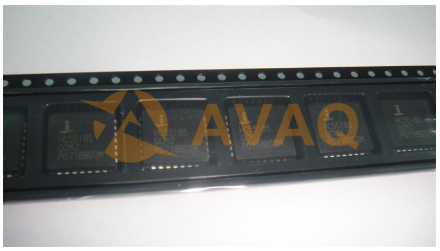
HC55185GCMZ

SLIC 1-CH 53dB 45mA 5V/-18V/-24V/-28V 28-Pin PLCC

Manufacturer:	Rochester Electronics Incorporated
Package/Case:	PLCC28
Product Type:	Communication & Networking ICs
Lifecycle:	Aftermarket



Images are for reference only

Inquiry

General Description

The RSLIC-VoIP family of ringing subscriber line interface circuits (RSLIC) supports analog Plain Old Telephone Service (POTS) in short and medium loop length, wireless and wireline applications. Ideally suited for remote subscriber units, this family of products offers flexibility to designers with high ringing voltage and low power consumption system requirements. The RSLIC-VoIP family operates to 100V which translates directly to the amount of ringing voltage supplied to the end subscriber. With the high operating voltage, subscriber loop lengths can be extended to 500Ω (i.e., 5,000 feet) and beyond. Other key features across the product family include: low power consumption, ringing using sinusoidal or trapezoidal waveforms, robust auto-detection mechanisms for when subscribers go on or off hook, and minimal external discrete application components. Integrated test access features are also offered on selected products to support loopback testing as well as line measurement tests. There are five product offerings of the HC55185 with each version providing voltage grades of high battery voltage and longitudinal balance. The voltage feed amplifier design uses low fixed loop gains to achieve high analog performance with low susceptibility to system induced noise.

Key Features

Onboard ringing generation

Compatible with existing HC5518x devices

Low standby power consumption (75V, 65mW)

Reduced idle channel noise

Programmable transient current limit

Improved off-hook software interface

Integrated MTU DC characteristics

Low external component count

Silent polarity reversal

Pulse metering and on-hook transmission

Tip open ground start operation

Balanced and unbalanced ringing

Thermal shutdown with alarm indicator

28 Ld surface mount packaging

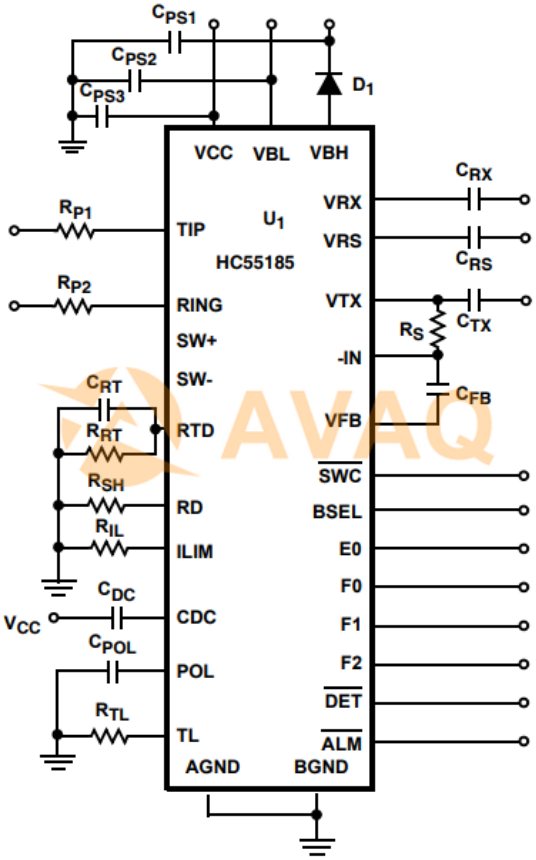
Reduced footprint micro leadframe packaging

Dielectric isolated (DI) high voltage design

QFN package:
Compliant to JEDEC PUB95 MO-220 QFN - Quad flat no leads - Product outline

Near chip scale package footprint; Improves PCB efficiency and has a thinner profile

Pb-free plus anneal available (RoHS compliant)



Recommended For You

HC55185CIMZ

Rochester Electronics Incorporated

PLCC28

HC55185GCR

Rochester Electronics Incorporated

QFN

HC55185ECMZ

Rochester Electronics Incorporated

PLCC28

HC55185AIMZ

Rochester Electronics Incorporated

PLCC28

HC55185BIM

Rochester Electronics Incorporated

PLCC

HC55185CIM96

Rochester Electronics Incorporated

PLCC-28

HC55185BIMZ

Rochester Electronics Incorporated

PLCC28

HC9P5509B3999-003

Rochester Electronics Incorporated

SOP28

HC55185DIM96

Rochester Electronics Incorporated

PLCC

HC55185GIMZ

Rochester Electronics Incorporated

PLCC28

CD22204E

Rochester Electronics Incorporated

DIP14

TCM320AC37CDW

Rochester Electronics Incorporated

SOP20

TLV320AC36IDWR

Rochester Electronics Incorporated

SOP20

TLC32044IN

Rochester Electronics Incorporated

DIP

TCM320AC36IDW

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